

SMCG Plastic-Encapsulate Diodes

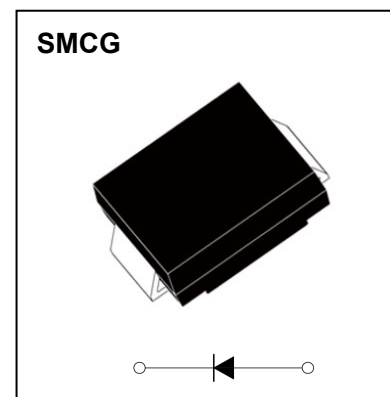
Super Fast Recovery Rectifier Diode

Features

- I_o 3A
- VRRM 50V-600V
- Low forward voltage drop
- High surge current capability
- Glass passivated chip junction

Mechical Data

- Case: JEDEC DO-214AB molded plastic
- Molding compound: UL flammability classification rating 94V-0
- Terminals: Tin plated leads, solderable per J-STD-002 and JESD22-B102
- Polarity: Color band denotes cathode end



Limiting Values (Absolute Maximum Rating)

Item	Symbol	Unit	Test Conditions	ES3							
				A	B	C	D	E	G	H	J
Repetitive Peak Reverse Voltage	V_{RRM}	V		50	100	150	200	300	400	500	600
Maximum RMS Voltage	V_{RMS}	V		35	70	105	140	210	280	350	420
Maximum DC blocking Voltage	V_{DC}	V		50	100	150	200	300	400	500	600
Average Forward Current	$I_{F(AV)}$	A	60HZ Half-sine wave, Resistance load, $T_L=80^{\circ}C$	3.0							
Surge(Non-repetitive)Forward Current	I_{FSM}	A	60Hz Half-sine wave ,1 cycle , $T_a=25^{\circ}C$	100							
Junction Temperature	T_J	$^{\circ}C$		-55~+150							
Storage Temperature	T_{STG}	$^{\circ}C$		-55 ~ +150							

Electrical Characteristics ($T_a=25^{\circ}C$ Unless otherwise specified)

Item	Symbol	Unit	Test Condition		ES3							
					A	B	C	D	E	G	H	J
Peak Forward Voltage	V _F	V	I _F =3.0A		0.95				1.25		1.70	
Maximum reverse recovery time	t _{rr}	ns	I _F =0.5A,I _R =1.0A,I _{rr} =0.25A		35							
Peak Reverse Current	I _{RRM1}	μA	V _{RM} =V _{RRM}	T _a =25℃	5							
	T _a =125℃			100								
Thermal Resistance(Typical)	R _{θJ-A}	℃/W	Between junction and ambient		47							
	Between junction and terminal		13									
	R _{θJ-L}	Between junction and case		12								
Juction Capacitance (Typical)	C _J	pF	Measured at 1.0MHz and applied reverse voltage of 4.0 volts.		60				35			

Typical Characteristics

FIG.1: FORWARD CURRENT DERATING CURVE

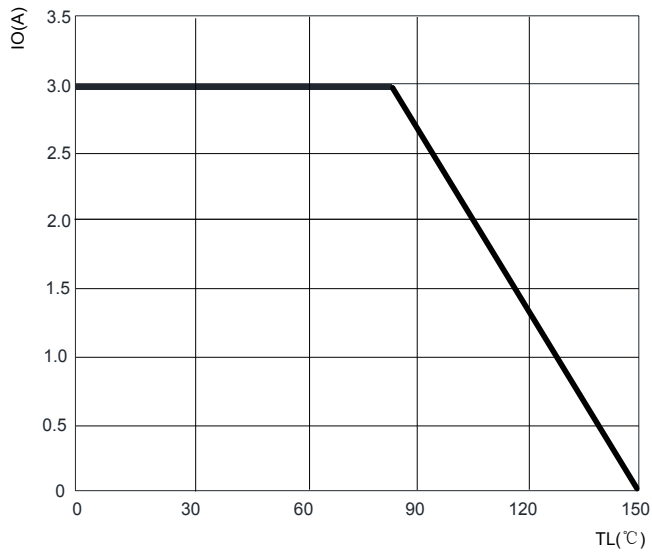


FIG.2: MAXIMUM NON-REPETITIVE FORWARD URGE CURRENT

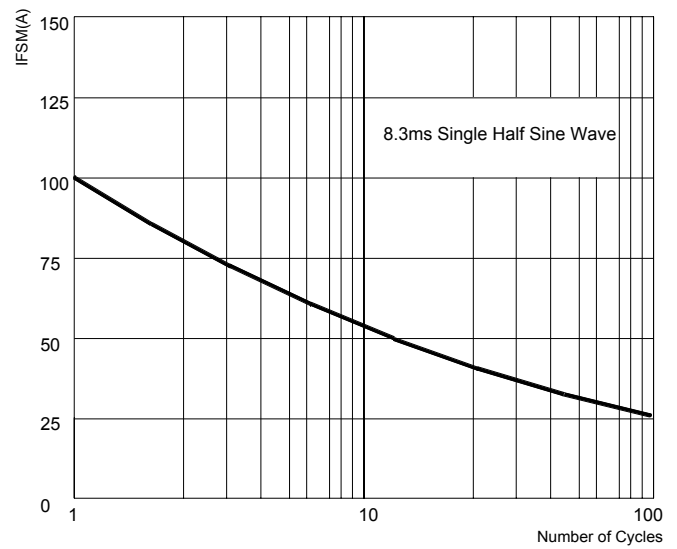


FIG.3: TYPICAL FORWARD CHARACTERISTICS

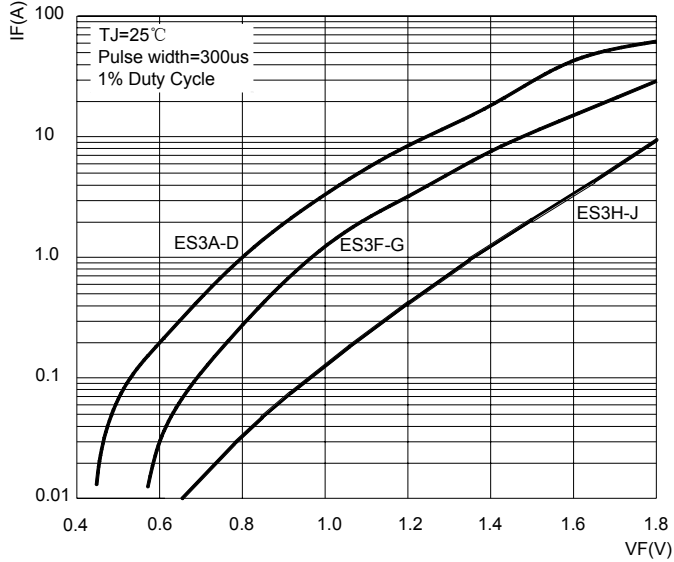


FIG.4: TYPICAL REVERSE CHARACTERISTICS

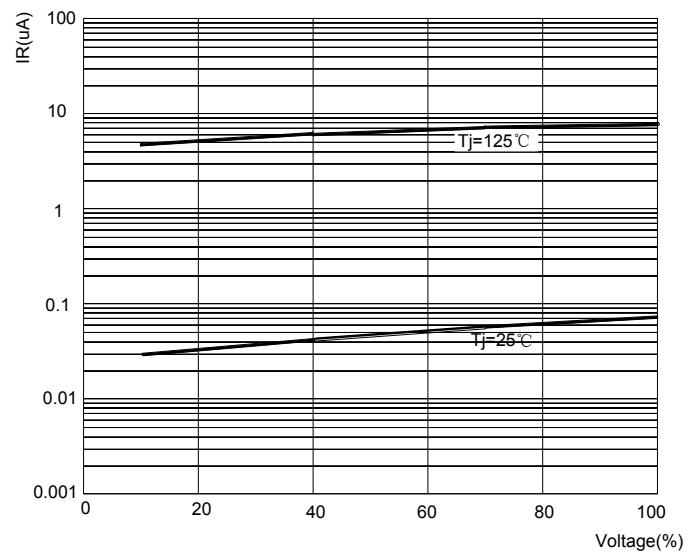
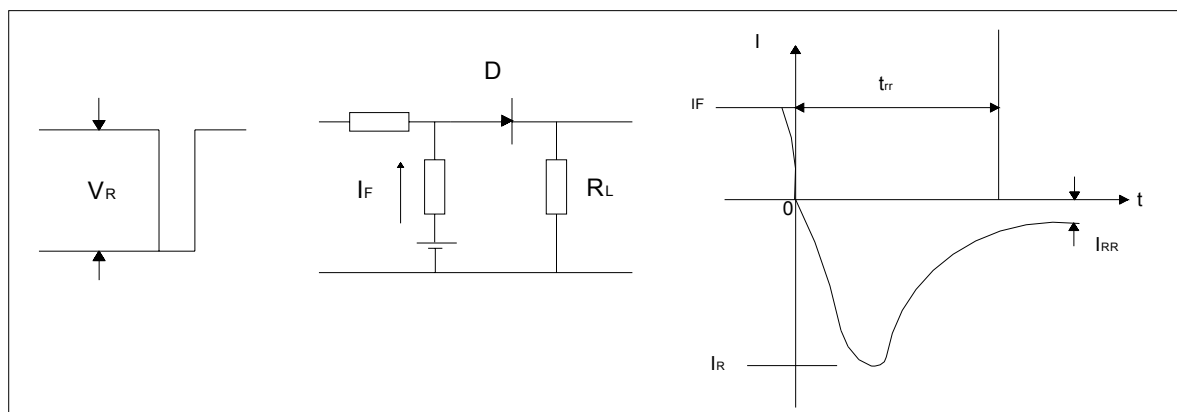
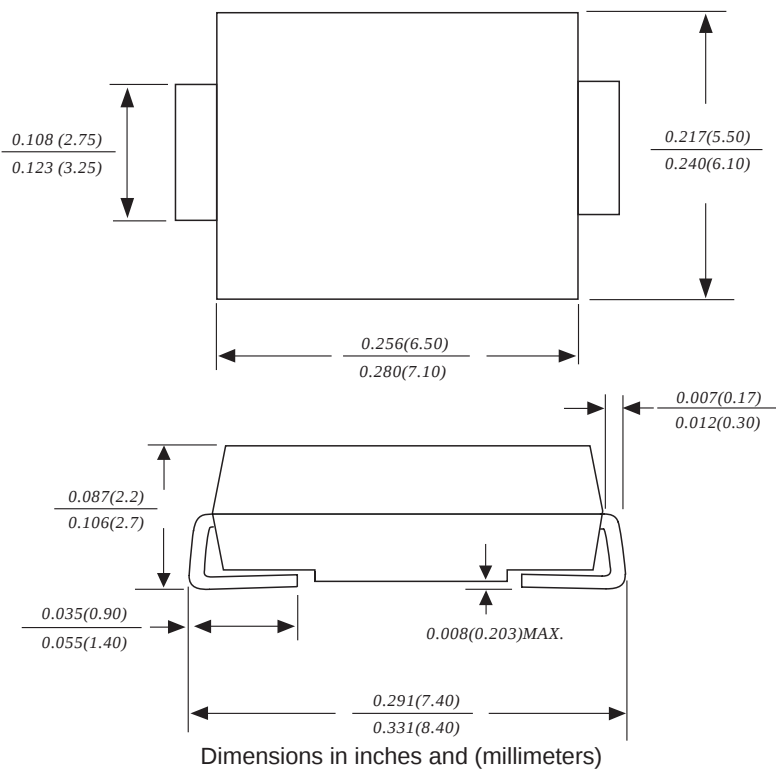


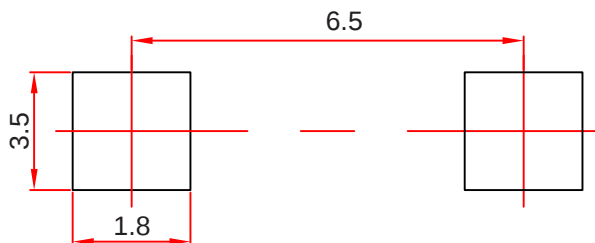
FIG.5: Diagram of circuit and Testing wave form of reverse recovery time



SMCG Package Outline Dimensions



SMCG Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05mm$.
3. The pad layout is for reference purposes only.

Ordering Information

Part Number	Package	Shipping Quantity
ES3A-ES3J	SMCG	3000/tape&Reel

Marking Diagram



X: From A To J

Reel Taping Specifications For Surface Mount Devices–SMCG

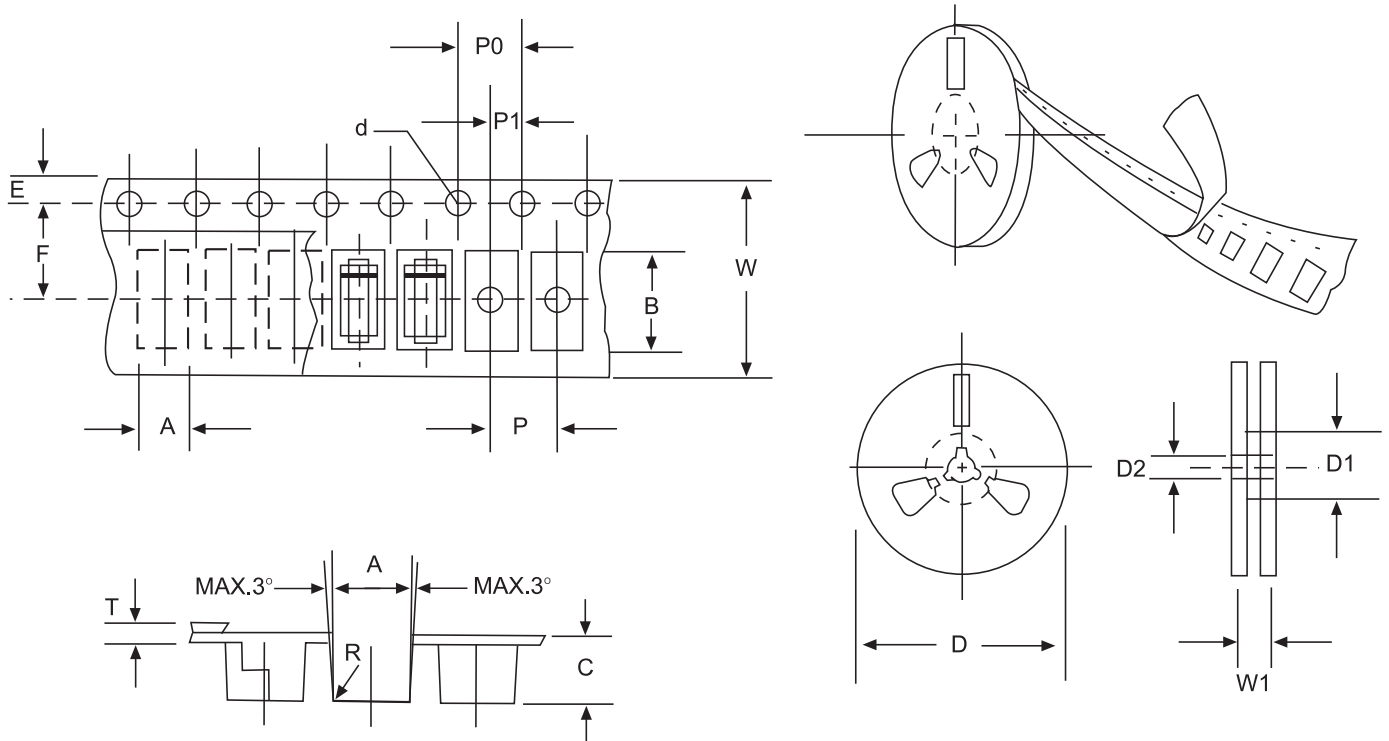


FIG: CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING

ITEM	SYMBOL	SMCG mm(inch)
Carrier width	A	6.05±0.1(0.238±0.004)
Carrier length	B	8.31±0.1(0.327±0.004)
Carrier depth	C	2.70±0.1(0.106±0.004)
Sprocket hole	d	1.55±0.05(0.061±0.002)
Reel outside diameter	D	330±2.0(13±0.079)
Reel inner diameter	D1	75±1.0 (2.95 ±0.039)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Stroket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	7.65±0.05(0.301±0.002)
Punch hole pitch	P	8.0±0.1(0.315±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Totall tape thickness	T	0.3±0.1 (0.012±0.004)
Tape width	W	16.0±0.2(0.630±0.008)
Reel width	W1	24.0±2.0(0.945±0.079)

NOTE:Devices are packde in accordance with EIA standard RS-481-A and specification given above.